



## Material Content Data Sheet



Sales Product Name	BSO110N03MS G			Issued		11. December 2019		
MA#	MA000466282							
Package	PG-DSO-8-39			Weight*		83.37 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.614	0.74	0.74	7361	7361
leadframe	inorganic material	phosphorus	7723-14-0	0.010	0.01		123	
	non noble metal	zinc	7440-66-6	0.041	0.05		491	
	non noble metal	iron	7439-89-6	0.820	0.98		9830	
	non noble metal	copper	7440-50-8	33.276	39.91	40.95	399119	409563
wire	non noble metal	copper	7440-50-8	0.235	0.28	0.28	2823	2823
encapsulation	organic material	carbon black	1333-86-4	0.236	0.28		2829	
	plastics	epoxy resin	-	7.313	8.77		87711	
	inorganic material	silicondioxide	60676-86-0	39.630	47.53	56.58	475336	565876
leadfinish	non noble metal	tin	7440-31-5	0.814	0.98	0.98	9761	9761
plating	noble metal	silver	7440-22-4	0.073	0.09	0.09	870	870
glue	plastics	epoxy resin	-	0.047	0.06		562	
	noble metal	silver	7440-22-4	0.265	0.32	0.38	3184	3746
*deviation	< 10%	Sum in total:			100.00			1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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